



05-23-2003

Atty. Docket No.: 3887-0120P

Page 1 of 1



SHEET

102455291

To the Director of the U.S. Patent and Trademark Office:
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

[FAMILY NAME (ALL CAPS), Given Name]

LEE, Sung-Kwon

KIM, Dong-Sauk

5-20-03

Additional name(s) of conveying party(ies) attached?

☐ YES ☒ NO

2. Name and address of receiving party(ies)

Name: HYNIX SEMICONDUCTOR INC.

Internal Address:

Street Address: San 136-1, Ami-ri, Bubal-eub

City: Ichon-shi State: Kyoungki-do ZIP:

Country: Republic of Korea Postal Code: 467-860

Additional name(s) & address(es) attached? ☐ YES ☒ NO

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other:

Execution Date: December 11, 2002, respectively

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s).

10/314,214

B. Patent No.(s).

Additional numbers attached? ☐ YES ☒ NO

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: BIRCH, STEWART, KOLASCH & BIRCH, LLP

Street Address: P.O. BOX 747

City: FALLS CHURCH State: VA ZIP: 22040-0747

Country: USA

6. Total No. of applications/patents involved: One (1)

7. Total fee (37 C.F.R. § 3.41): \$40.00

☒ Enclosed☒ Authorized to be charged to deposit account,
if no fee attached.

8. Deposit account number: 02-2448

(Attach triplicate copy of this page
if paying by deposit account)

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9. Statement and signature.

Joseph A. Kolasch, #22,463

Name of Person Signing/Reg. No.

Signature

May 20, 2003

Date

Total number of pages including cover sheet, attachments, and document: Three (3)

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(Rev. 04/30/03)

PATENT
REEL: 014085 FRAME: 0822

BIRCH, STEWART, KOLASCH & BIRCH, LLP
UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Application No. 10/314214Filed December 9, 2002WHEREAS, LEE, SUNG-KWON and KIM, DONG-SAUK

Insert Name(s)
of Inventor(s)

(hereinafter designated as the undersigned) has(have) invented certain new and useful improvements in

METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

Insert Title
of Invention

for which an application for Letters Patent of the United States of America has been executed by the undersigned(except in the case of a provisional application).

Insert Date
of Signing of
Application

On December 11, 2002 : andWHEREAS, Hynix Semiconductor Inc.

Insert Name
of Assignee

Of San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860, Republic of Korea

Insert Address
of Assignee

Its hers, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefore in the United States of America and

☐ in any foreign countries.

CHECK BOX
IF APPROPRIATE

NOW, THEREFORE, in consideration of the sum of Ten Dollars(\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has(have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its, territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefore in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any all foreign countries:

And to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned and that he has(they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation or this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date December 11, 2002

Name Inventor(Signature)

LEE, SUNG-KWON

Date December 11, 2002

Name Inventor(Signature)

KIM, DONG-SAUK

Date

Name Inventor(Signature)

Date

Name Inventor(Signature)

Date

Name Inventor(Signature)